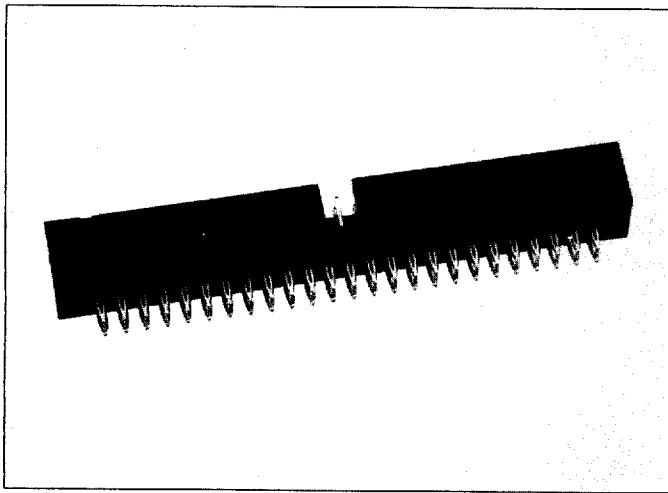


HEADERS



Low Profile Press-Fit Headers .025" Sq. Post

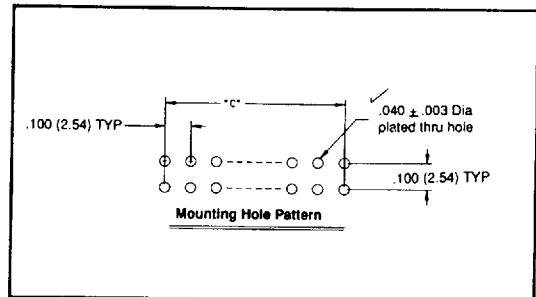
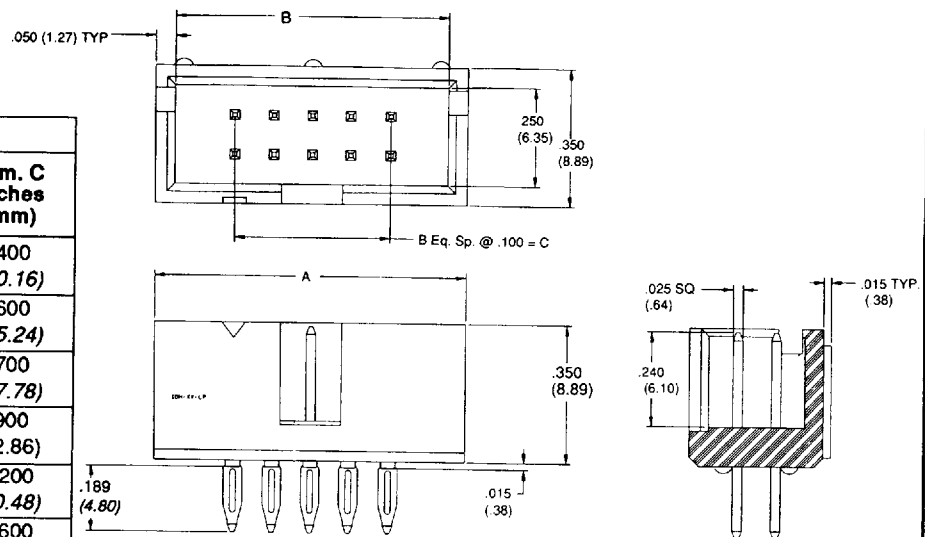
IDH-LP Series



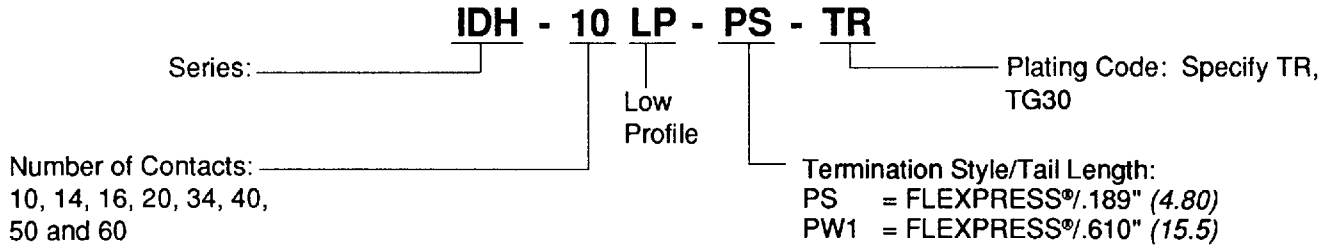
- Designed for applications where space is critical
- FLEXPRESS® compliant pins permit solderless mounting
- Fool-proof socket polarization
- Optional ROBEX® better-than-gold plating

DIN/HDC BACKPLANE

Tabulations			
No. of Contacts	Dim. A. Inches (mm)	Dim. B Inches (mm)	Dim. C Inches (mm)
10	.800 (20.32)	.700 (17.78)	.400 (10.16)
14	1.000 (25.40)	.900 (22.86)	.600 (15.24)
16	1.100 (27.94)	1.000 (25.40)	.700 (17.78)
20	1.300 (32.02)	1.200 (30.48)	.900 (22.86)
26	1.600 (40.64)	1.500 (38.10)	1.200 (30.48)
34	2.000 (50.80)	1.900 (48.26)	1.600 (40.64)
40	2.300 (58.42)	2.200 (55.88)	1.900 (48.26)
50	2.800 (71.12)	2.700 (68.58)	2.400 (60.96)
60	3.300 (83.82)	3.200 (81.28)	2.900 (73.66)



How to Order IDH-LP Series



For application push tooling; order number IDH-PT-XX (see page 342)

Materials:

Body: Glass-filled, black polyester
Contact: Copper Alloy

Mounting

Information:

FLEXPRESS® Recommended

Plated Thru Hole

.0453 ± .001 (1.15 ± .0254) DIA
.0460 (1.17) Maximum after etchback
.001 (.0254) Minimum copper plating thickness
.0003 (.0076) Minimum tin plating thickness
.040 ± .003 (1.02 ± .0762) finished PTH DIA

Performance

Characteristics:

Temperature Range: -65 C to + 105 C
Contact Resistance: 20 Milliohms Max.
Insulation Resistance: 5000 Megaohms Min.
Dielectric Withstand Voltage: 500 volts DC
Current Rating: 1 Ampere at 25C ambient
Flammability: UL 94V-0

Plating Description:

Suffix TR = 10 μinch (.254μm) minimum
ROBEX® on contact area.
100 μinch (2.54 μm) minimum
Tin on terminal area.

TG30 = 30 μinch (.762 μm) minimum
Gold on contact area.
100 μinch (2.54 μm) minimum
Tin on terminal area.

All options include an underplate of 50 μinch
(1.27 μm) minimum Nickel.